D2661, APRIL 1982-REVISED MARCH 1988

- Fully Buffered to Offer Maximum Isolation from External Disturbance
- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

These devices contain two independent J-K negative-edge-triggered flip-flops. A low level at the preset and clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the J and K inputs meeting the setup time requirements are transferred to the outputs on the negative-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by tying J and K high.

The SN54LS112A and SN54S112 are characterized for operation over the full military temperature range of ~55°C to 125°C. The SN74LS112A and SN74S112A are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)

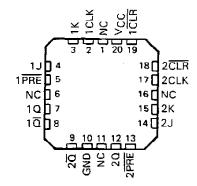
	INI	ουπ	PUTS			
PRE	CLR	CLK	J	K	a	Q
L	Н	X	Х	Х	Н	L
н	L	×	Х	X	L	Н
L	L	×	х	Х	H [†]	H [†]
н	н	1	L	L	ΩO	₫₀
H	Н	1	Н	L	Н	L
Н	H	1	L	н	L	н
Н	Н	1	Н	н	TOG	GLE
Н	<u> H</u>	Н	_ X	х	αo	₫o

[†] The output levels in this configuration are not guaranteed to meet the minimum levels for V_{OH} if the lows at preset and clear are near V_{IL} minimum. Furthermore, this configuration is nonstable; that is, it will not persist when either preset or clear returns to its inactive (high) level.

SN54LS112A, SN54S112 . . . J OR W PACKAGE SN74LS112A, SN74S112A . . . D OR N PACKAGE (TOP VIEW)

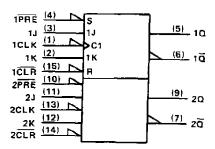
_	_		
1CLK[]1	\cup_{16}	□vcc
1K []2	15	1 CLR
1J[]3	14	2CLR
1PRE]4	13	2CLK
10[]5	12	<u></u> 2κ
10[]6	11	2J
20 [7	10	2PRE
GND [8	9	20

SN54LS112A, SN54S112...FK PACKAGE (TOP VIEW)



NC-No internal connection

logic symbol‡

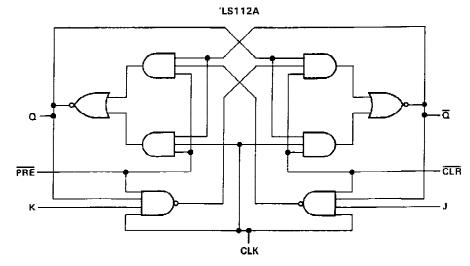


[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

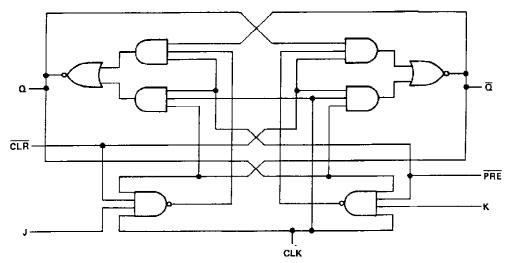
Pin numbers shown are for D, J, N, and W packages.

SN54LS112A, SN54S112, SN74LS112A, SN74S112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

logic diagrams (positive logic)

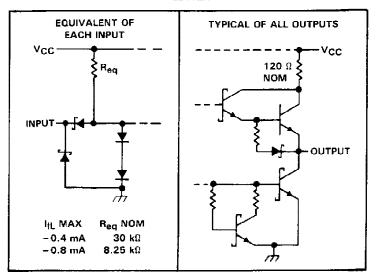


SN54S112, SN74LS112A

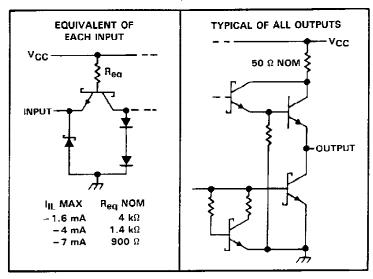


schematics of inputs and outputs

'LS112A



SN54S112, SN74S112A



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V	
Input voltage: 'LS112A	7 V	
SN54LS112, SN74LS112A	5 V	
Operating free-air temperature range: SN54'	٥°C	
SN74') °C	
Storage temperature range65 °C to 150	°C	

NOTE 1: Voltage values are with respect to network ground terminal.

SN54LS112A, SN74LS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

recommended operating conditions

			SN	154LS11	2A	SN	74LS11	2A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	٧
ЮН	High-level output current				-0.4			-0.4	mΑ
OL	Low-level output current				4			8	mA
fclock	Clock frequency		0		30	0		30	MHz
	Pulse duration	CLK high	20			20			
t _W	ruise duration	PRE or CLR low	25	-		25	<u></u>		ns
		Data high or low	20		**	20			
t _{su}	Set up time-before CLK↓	CLR inactive	25			25			ns
		PRE inactive	20			20			
th	Hold time-data after CLK1		0			0			Π\$
TA	Operating free-air temperature		- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	BANETER	TEST	CONDITIONS†		SN	154LS11	I2A	SI	174LS11	2A	
Ρ,	ARAMETER	IEST	CONDITIONS		MIN	TYP!	MAX	MIN	TYP‡	MAX	UNIT
v_{lK}		V _{CC} = MIN,	I _I = -18 mA				-1.5			1.5	V
Vон		V _{CC} = MIN, I _{OH} = -0.4 mA	$V_{IH} = 2 V$,	V _{IL} ≠ MAX,	2.5	3.4		2.7	3.4		٧
.,		V _{CC} = MIN, I _{OL} = 4 mA	V _{IL} = MAX,	V _{IH} = 2 V,		0.25	0.4		0.25	0.4	· ·
VOL		V _{CC} = MIN, I _{OL} = 8 mA	$V_{IL} = MAX,$	V _{IH} = 2 V,					0.35	0.5	V
	J or K						0.1			0.1	
f _l	CLR or PRE	VCC = MAX,	$V_I = 7 V$				0.3			0.3	mA
	CLK						0.4			0.4	
	J or K						20			20	
ΉΗ	CLR or PRE	V _{CC} = MAX,	V_{\parallel} = 2.7 \vee		-		60			60	μА
	CLK						80			80	<u> </u>
1	J or K	Vcc = MAX,	Vi = 0 4 V				-0.4			-0.4	mA
ll .	All other	*CC = 1810011,	· · · · · · · · · · · · · · · · · · ·				-0.8			-0.8	
los §		VCC = MAX.	see Note 2		20		- 100	- 20		- 100	mΑ
ICC (T	otal)	V _{CC} = MAX,	see Note 3			4	6		4	6	mΑ

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡]All typical values are at V_{CC} = 5 V, T_A = 25 °C.

Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

NOTES: 2. For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with $V_0 = 2.25 \text{ V}$ and 2.125 V for the '54 family and the '74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

^{3.} With all outputs open, ICC is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, V_{CC} = 5 V, T_A = 25 °C (see Note 4)

PARAMETER	FROM (INPUT)	TQ {OUTPUT)	TEST CO	NDITIONS	MIN	ТҮР	MAX	UNIT
fmax					30	45		MHz
t P LH	CLR. PRE or CLK	Q or Q	$R_L = 2 k\Omega$,	C _L = 15 pF		15	20	กร
†PHL	CLM, PRE OF CLK	2012				15	20	пs

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

SN54S112, SN74S112A DUAL J-K NEGATIVE EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

recommended operating conditions

			S	N54S1	12	SI	174611	2A	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	DINIT
VCC	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
ViH	High-level input voltage	-	2			2			V
VIL	Low-level input voltage				0.8			0.8	٧
ЮН	High-level output current				- 1			– 1	mA
loL	Low-level output current				20			20	mA
		CLK high	6			6		.,,	
tw	Pulse duration	CLK low	6.5		- -	6.5			пѕ
		PRE or CLR low	8			8			
t _{su}	Set up time-before CLK↓	Data high or low	7			7			กร
th	Hold time-data after CLK↓		0			0			ns
TA	Operating free-air temperature		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DAMETED	TECT	CONDITIONS		5	N54S1	2	SI	N74S11	2 A	LIBUT
PA	RAMETER	IESI	CONDITIONS		MIN	TYP [‡]	MAX	MIN	TYP‡	MAX	UNIT
VIK		V _{CC} = MIN,	lj = -18 mA				-1.2			-1.2	٧
VoH		V _{CC} = MIN, I _{OH} = -1 mA	V _{IH} = 2 V,	VIL = MAX,	2.5	3.4		2.7	3.4		٧
VOL		V _{CC} = MIN, I _{OL} = 20 mA	V _{IH} = 2 V,	V _{IL} - 0.8 V,			0.5			0.5	V
I _I			V ₁ = 5.5 V				1			1	mA
1.	J or K	VCC = MAX.	V 27V				50			50	μА
ΉН	All other	T ACC = MINY	V = 2.7 V				100			100	μπ
	Jor K						-1.6			-1.6	
	CLR [§]],,	V 05V				-7			-7	mΑ
ΙΙΓ	PRE §	V _{CC} = MAX,	VI = 0.5 V			•	-7	1		-7	MA
	CLK	1					-4			- 4	
los¶		V _{CC} = MAX			-40	•	- 100	-40		~ 100	mA
ICC#		V _{CC} = MAX,	see Note 3			15	25		15	25	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

[§]Clear is tested with preset high and preset is tested with clear high.

Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

[#]Values are average per flip-flop.

NOTE 3: With all outputs open, I_{CC} is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, VCC = 5 V, TA = 25 °C (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				80	125		MHz
tPLH	PRE or CLR	Q or Q			4	7	ns
4	PRE or CLR (CLK high)	Ō or O	D. 200.0 0. 15 -5		5	7	
†PHL	PRE or CLR (CLK low)	a or a	$R_L = 280 \Omega$, $C_L = 15 pF$		5	7	ns
^t PLH	CLK	Q or $\overline{\mathbf{Q}}$			4	7	nŝ
tPHL .	CER	Q 01 Q			5	7	ns

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

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29-May-2025

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
JM38510/07102BEA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/07102B EA
JM38510/07102BEA.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/07102B EA
JM38510/07102BFA	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 07102BFA
JM38510/07102BFA.A	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 07102BFA
JM38510/30103B2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30103B2A
JM38510/30103B2A.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30103B2A
JM38510/30103BEA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30103BEA
JM38510/30103BEA.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30103BEA
JM38510/30103BFA	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30103BFA
JM38510/30103BFA.A	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30103BFA
M38510/07102BEA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/07102B EA
M38510/07102BFA	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 07102BFA
M38510/30103B2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30103B2A
M38510/30103BEA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30103BEA
M38510/30103BFA	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30103BFA
SN54LS112AJ	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS112AJ
SN54LS112AJ.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS112AJ
SN54S112J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54S112J





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29-May-2025

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN54S112J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54S112J
SN74LS112AD	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	0 to 70	LS112A
SN74LS112ADR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS112A
SN74LS112ADR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS112A
SN74LS112AN	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS112AN
SN74LS112AN.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS112AN
SN74LS112ANSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS112A
SN74LS112ANSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS112A
SN74S112AN	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74S112AN
SN74S112AN.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74S112AN
SNJ54LS112AFK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS 112AFK
SNJ54LS112AFK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	or Pkg Type -55 to 125	
SNJ54LS112AJ	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS112AJ
SNJ54LS112AJ.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS112AJ
SNJ54LS112AW	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS112AW
SNJ54LS112AW.A	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS112AW
SNJ54S112FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S 112FK
SNJ54S112FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S 112FK
SNJ54S112J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S112J
SNJ54S112J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S112J
SNJ54S112W	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S112W
SNJ54S112W.A	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S112W

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

PACKAGE OPTION ADDENDUM

www.ti.com 29-May-2025

- (3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54LS112A, SN74LS112A:

Catalog: SN74LS112A

Military: SN54LS112A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2025

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS112ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS112ANSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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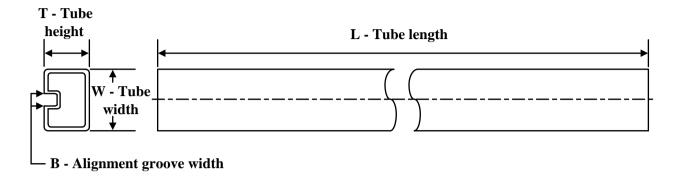
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS112ADR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LS112ANSR	SOP	NS	16	2000	353.0	353.0	32.0



www.ti.com 24-Jul-2025

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/07102BFA	W	CFP	16	25	506.98	26.16	6220	NA
JM38510/07102BFA.A	W	CFP	16	25	506.98	26.16	6220	NA
JM38510/30103B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/30103B2A.A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/30103BFA	W	CFP	16	25	506.98	26.16	6220	NA
JM38510/30103BFA.A	W	CFP	16	25	506.98	26.16	6220	NA
M38510/07102BFA	W	CFP	16	25	506.98	26.16	6220	NA
M38510/30103B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/30103BFA	W	CFP	16	25	506.98	26.16	6220	NA
SN74LS112AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS112AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS112AN.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS112AN.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74S112AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74S112AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74S112AN.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74S112AN.A	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS112AFK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS112AFK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS112AW	W	CFP	16	25	506.98	26.16	6220	NA
SNJ54LS112AW.A	W	CFP	16	25	506.98	26.16	6220	NA
SNJ54S112FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54S112FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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